



# **SPECIFICATIONS**

#### GENERAL

Contact Arrangement	4PDT (4 Form C)
-	Magnetic Latching
Weight	2.2 oz approx.
Designed to meet the require	ments of MIL-PRF-83536

### PERFORMANCE

#### Contact Rating (Note 1)

Resistive	
	115/208V 400 Hz
	(Case Grounded)
Inductive	
	115/208V 400 Hz
	(Case Grounded)
	2.5 Amps @ 115/208V 60 Hz
	(Case Grounded)
Motor	
	115/208V 400 Hz
	(Case Grounded)
	2 Amps @ 115/208V 60 Hz
1	(Case Grounded)
Lamp	
	115/208V 400 Hz
	(Case Grounded)
	1.5 Amps @ 115/208V 60 Hz
	(Case Grounded)
1.15	
Life100,000	operations minimum @ rated
	resistive load, 125°C
Latch/Reset Power	500 mw approx.

# Miniature 10 Amps • 4PDT Magnetic Latching To MIL-PRF-83536

Latch/Reset Time:	DC Coil	AC Coil
	15 ms max	50 ms max
Excluding bounce time a	t nominal coil volt	age
Contact Bounce Time		1 ms max
	@ rated contact lo	bad, 28 VDC
Contact Voltage Drop:		
	4 - 0	<b>•</b> • • •

Before Life	150 mv max @ 10 Amps
	and 6 VDC
After Life	175 mv max @ 10 Amps
	and 6 VDC

#### ENVIRONMENTAL

Temperature Range	70°C to +125°C
Vibration (Note 2)	0.12" DA 10 - 70 Hz
	30 G's 70 - 3,000 Hz
Shock (Operating)(Note 2)	200 G's 6 ms

### ELECTRICAL CHARACTERISTICS

Duty Cycle Insulation Resistance	
Dielectric Strength:	@ 500 v 25 C
Sea Level:	
Contact to Case	1 250 VRMS
Contact to Coil	
Coil to Case	
Across Open Contacts	
80,000 Feet:	,
All Points	

#### MIL-PRF-83536/18 QUALIFIED to ER level L

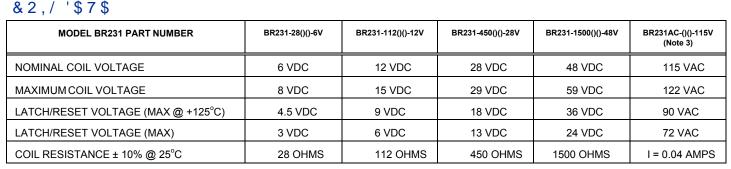
#### Notes

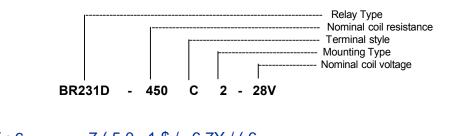
- 1. For other ratings consult the factory.
- 2. For applications requiring higher shock and vibration, consult the factory.

3. AC coil line frequency 50 to 400 Hz.

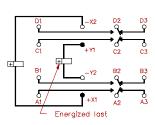
April 2015 Rev .8



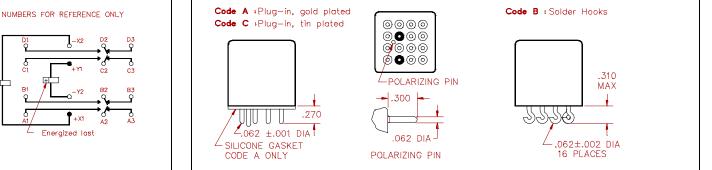




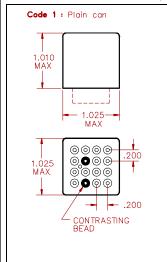


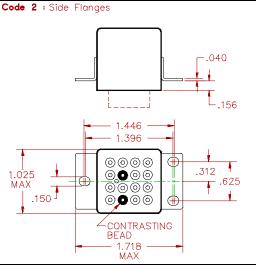


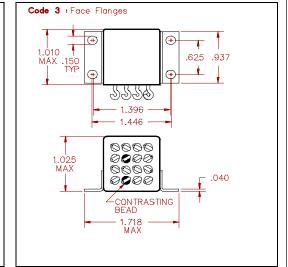
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- · Unless otherwise specified, all tests made at nominal coil voltages, @ 25°C.
- For special coil variations, switching configurations, terminals styles and mounting types, consult the factory.
- · Unless otherwise specified, tolerances on decimal dimensions are ± .010".
- Specifications contained herein are subject to change without notice.



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